



P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$ $I_{D}(A)$		Q _g (Typ.)		
- 30	$0.0087 \text{ at V}_{GS} = -10 \text{ V}$	- 45 ^d	60		
- 30	0.0150 at $V_{GS} = -4.5 \text{ V}$	- 32	00		

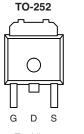
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

COMPLIANT HALOGEN FREE

APPLICATIONS

- · Power Switch
- Load Switch in High Current Applications
- DC/DC Converters



Drain Connected to Tab

P-Channel MOSFET

Ordering Information: SUD45P03-09-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20	1 v	
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	1-	- 45 ^d	
Continuous Diam Current (1) = 130 C)	T _C = 70 °C	I _D	- 42.5] A
Pulsed Drain Current	I _{DM}	- 100	7	
Avalanche Current	I _{AS}	- 35		
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	61	mJ
Mariana Barra Biantania	T _C = 25 °C	В	41.7 ^b	10/
Maximum Power Dissipation ^a	T _A = 25 °C°	$ P_D$ $-$	2.1	W
Operating Junction and Storage Temperature Ra	nge	T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Limit	Unit			
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/M			
Junction-to-Case (Drain)	R _{thJC}	3	°C/W			

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.c. When Mounted on 1" square PCB (FR-4 material).
- d. Package limited.

SUD45P03-09

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	,			, ,.			
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 30			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V _{DS} = - 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	μΑ	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 150 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 50			Α	
		V _{GS} = - 10 V, I _D = - 20 A		0.0072	0.0087	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 15 A		0.0125	0.0150		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 20 A		45		S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			2700		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = - 15 V, f = 1 MHz		515			
Reverse Transfer Capacitance	C _{rss}			445			
Total Gate Charge ^c	Q_g			60	90	nC	
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 20 A		9.3			
Gate-Drain Charge ^c	Q_{gd}			15			
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.5	5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			12	20		
Rise Time ^c	t _r	$V_{DD} = -15 \text{ V}, R_L = 1.5 \Omega$		11	20		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	60	ns	
Fall Time ^c	t _f			12	20		
Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b					
Continuous Current	Is				- 45	A	
Pulsed Current	I _{SM}				- 100		
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			27	40	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 10 A, dI/dt = 100 A/μs		1.3	2	Α	
Reverse Recovery Charge	Q _{rr}	1		20	30	nC	

Notes:

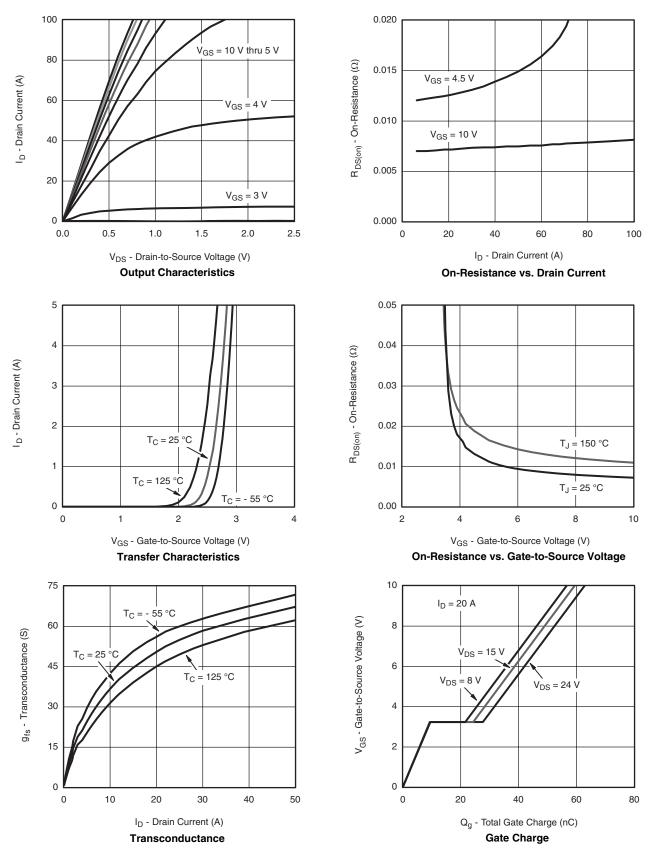
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





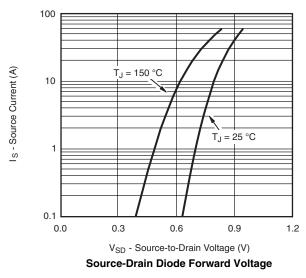
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

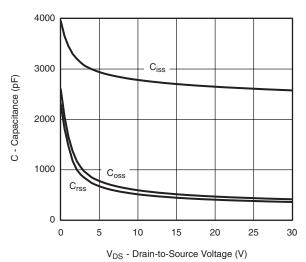


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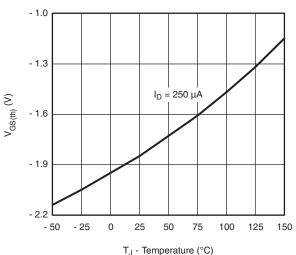




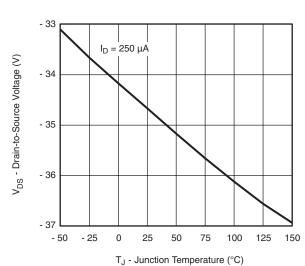
Capacitance

1.8 I_D = 20 Å $V_{GS} = 10 \text{ V}$ 1.5 R_{DS(on)} - On-Resistance (Normalized) 1.2 $V_{GS} = 4.5 \text{ V}$ 0.9 0.6 - 50 50 75 100 125 150 T_J - Junction Temperature (°C)

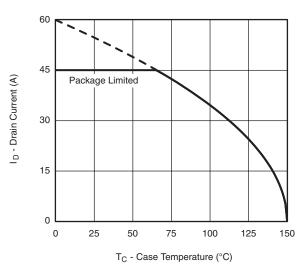
On-Resistance vs. Junction Temperature



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature

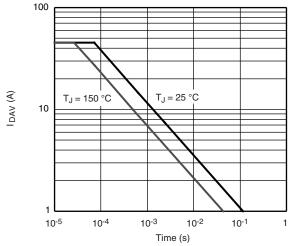


Current Derating

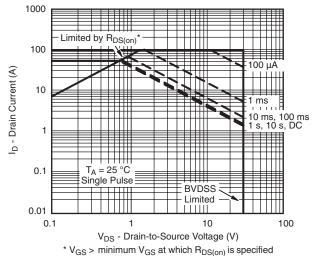


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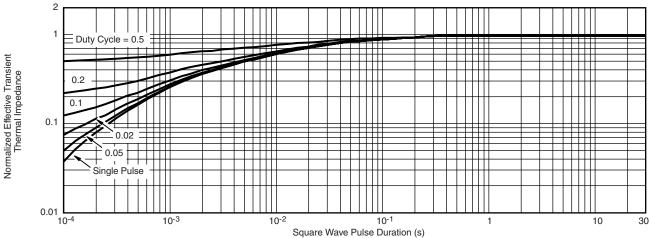
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Single Pulse Avalanche Current Capability vs. Time



Safe Operating Area



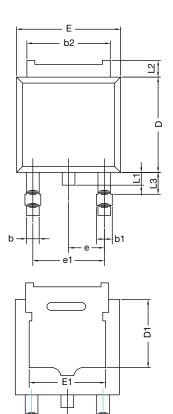
Normalized Thermal Transient Impedance, Junction-to-Case

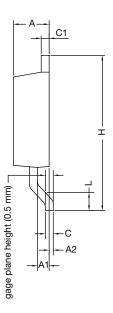
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TO-252AA CASE OUTLINE





	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
A2	0.030	0.127	0.001	0.005	
b	0.71	0.88	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.44	0.206	0.214	
С	0.46	0.58	0.018	0.023	
C1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
D1	4.10	4.45	0.161	0.175	
Е	6.48	6.73	0.255	0.265	
E1	4.49	5.50	0.177	0.217	
е	2.28	BSC	SC 0.090 BSC		
e1	4.57	BSC	0.180 BSC		
Н	9.65	10.41	0.380	0.410	
L	1.40	1.78	0.055	0.070	
L1	0.64	1.02	0.025	0.040	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.040	0.060	
ECN: T11-0110-Rev. L, 18-Apr-11 DWG: 5347					

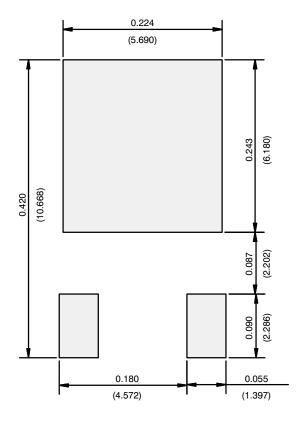
Note

• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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